

FEATURES

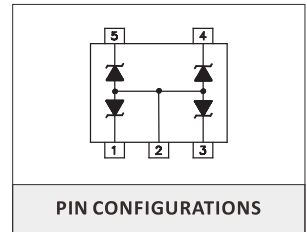
- >Ultra low leakage
- >Operating voltage: 5V
- >Low clamping voltage
- >Complies with following standards:
- >RoHS Compliant

APPLICATIONS

- >USB 2.0 power and data line
- >Set-top box and digital TV
- >Digital video interface (DVI)
- >Notebook Computers
- >SIM Ports
- >10/100 Ethernet

IEC COMPATIBILITY

- >IEC61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
- >IEC61000-4-4 (EFT) 40A (5/50ns)
- >IEC61000-4-5 (Lightning) 2A (8/20µs)



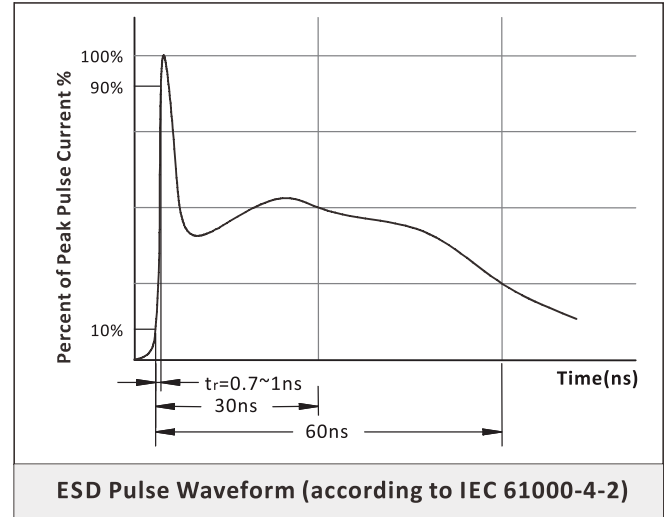
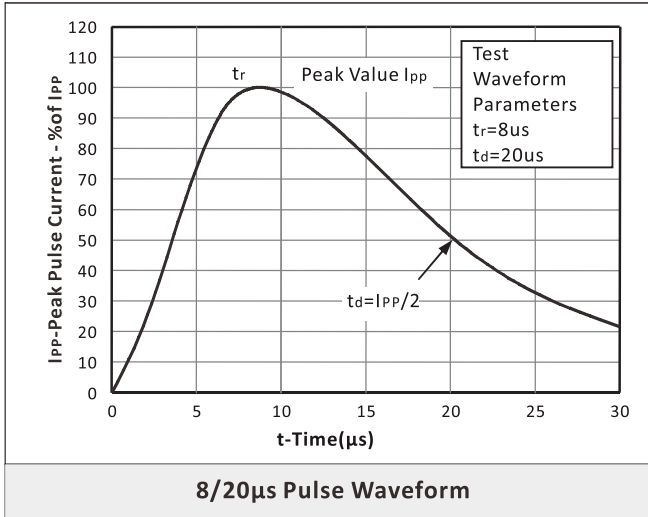
MAXIMUM RATINGS @ 25°C UNLESS OTHERWISE SPECIFIED

PARAMETER	SYMBOL	VALUE	UNIT
Peak Pulse Power (tp=8/20µs waveform)	PPP	30	Watts
Lead Soldering Temperature	TL	260(10 sec.)	°C
Operating Temperature Range	TJ	-55~125	°C
Storage Temperature Range	TSTG	-55~150	°C

ELECTRICAL CHARACTERISTICS PER LINE @ 25°C UNLESS OTHERWISE SPECIFIED

PART NUMBER	DEVICE MARKING	VRWM (V) Max.	VBR (V) Min.	IT (mA)	Vc @1A Max.	Vc		IR (uA) Max.	CT (pF) Typ.
						Max.	@A		
SELC0504T5	W2	5.0	6.0	1	9.8	15.0	2.0	1	8

CHARACTERISTIC CURVES

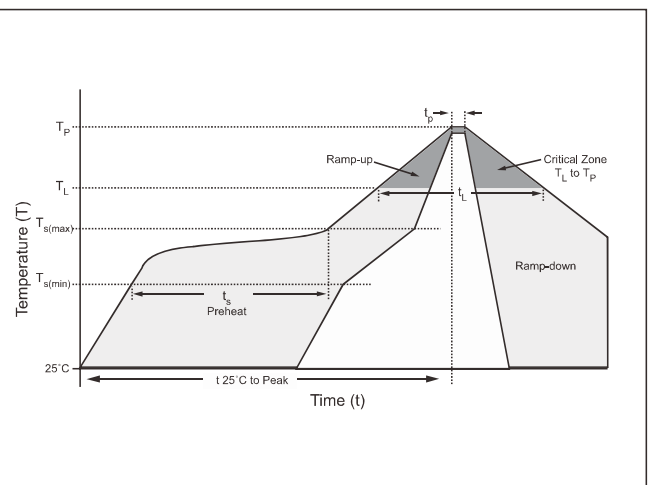


ENVIRONMENTAL CHARACTERISTICS

Testing Items	Technical Standards
High Temperature Reverse Bias Test	Temperature:150±3°C,Bias=80%V _{DRM} ;Time:168H
High Temperature Life Test	Temperature:150°C;Time:168H
High-Low Temperature Cycle Test	Temperature:From -40°C to 150°C;Dwell Time:30min,10-100 Cycles
High Temperature&High Humidity Test	Temperature:85°C.Humidity:85%; Time:168H
Pressure Cooker Test	Temperature:121°C,2 atm.Humidity:100%; Time:24H To 168H
Resistance Of Soldering Heat	Temperature:260±5°C;Time Of Dip Soldering:10s,3 Times

REFLOW PROFILE

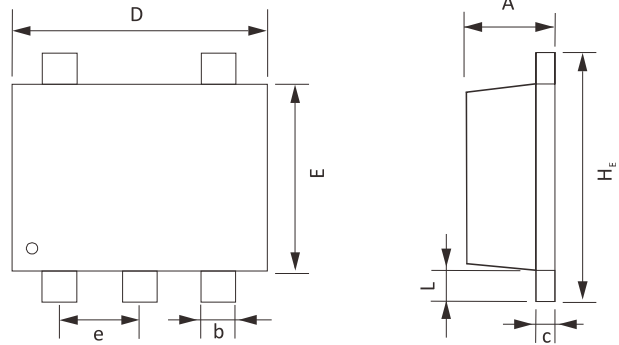
Reflow Condition		Lead-free assembly
Pre Heat	Temperature Min (Ts(min))	150°C
	Temperature Max (Ts(max))	200°C
	Time (min to max) (ts)	60 – 180 secs
Average ramp up rate (Liquidus Temp (TL) to peak)		3°C/second max
Ts(max)to TL - Ramp-up Rate		3°C/second max
Reflow	Temperature (TL) (Liquidus)	217°C
	Time (min to max) (ts)	60 – 150 seconds
Peak Temperature (Tp)		260°C
Time within 5°C of actual peak Temperature (tp)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (Tp)		8 minutes Max.
Do not exceed		260°C



SOT-553 PACKAGE INFORMATION

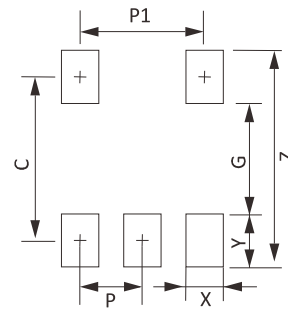
OUTLINE DIMENSIONS				
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.50	0.60	0.020	0.023
b	0.17	0.27	0.007	0.011
C	0.08	0.18	0.003	0.007
D	1.50	1.57	0.059	0.066
E	1.10	1.30	0.043	0.051
e	0.50 BSC.		0.020 BSC.	
L	0.10	0.30	0.004	0.012
H _E	1.50	1.70	0.059	0.067

NOTES	
1.	Controlling dimension: inches.
2.	Dimensions are exclusive of mold flash and metal burrs.



PAD LAYOUT DIMENSIONS		
DIM	MILLIMETERS	INCHES
C	1.35	0.053
G	0.90	0.035
P	0.50	0.020
P1	1.00	0.039
X	0.30	0.012
Y	0.45	0.018
Z	1.80	0.071

NOTES	
1.	Controlling dimension: inches.



ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SELC0504T5	SOT-553	3000PCS	7"

CONTACT US

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